TOSHIBA Schottky Barrier Rectifier Schottky Barrier Type

CUS05

Switching Mode Power Supply Applications Portable Equipment Battery Application

- Forward voltage: $V_{FM} = 0.37 \text{ V (max)} @I_F = 0.7 \text{ A}$
- Average forward current: IF (AV) = 1.0 A
- Repetitive peak reverse voltage: V_{RRM} = 20 V
- Suitable for high-density board assembly due to the use of a small Surface-mount package, US-FLATTM

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	20	V
Average forward current	I _{F (AV)}	1.0 (Note 1)	Α
Peak one cycle surge forward current (Non-repetitive)	I _{FSM}	20 (50 Hz)	Α
Junction temperature	Tj	-40 to 125	°C
Storage temperature range	T _{stg}	-40 to 150	°C

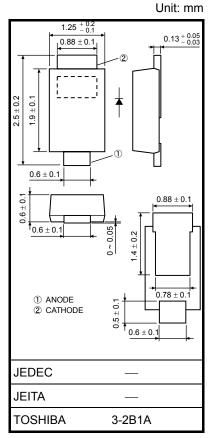
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the

reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ta = 66°C: Device mounted on a ceramic board (board size: 50 mm × 50 mm, Soldering land: 2 mm × 2 mm)

Rectangular waveform ($\alpha = 180^{\circ}$), $V_R = 10 \text{ V}$



Weight: 0.004 g (typ.)



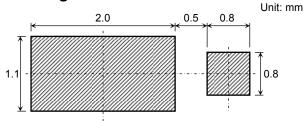
Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Peak forward voltage	V _{FM (1)}	I _{FM} = 0.1 A	_	0.25	_		
	V _{FM (2)}	I _{FM} = 0.7 A	_	0.33	0.37	V	
	V _{FM (3)}	I _{FM} = 1.0 A	_	0.39	_		
Repetitive peak reverse current	I _{RRM (1)}	V _{RRM} = 5 V	_	50	_	μА	
Repetitive peak reverse current	I _{RRM (2)}	V _{RRM} = 20 V	_	0.2	1.0	mA	
Junction capacitance	Cj	V _R = 10 V, f = 1.0 MHz	_	40	_	pF	
Thermal resistance (junction to ambient)	D	Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land: 2 mm × 2 mm) (board thickness: 0.64 mm)	_	_	75	- °C/W	
	R _{th (j-a)}	Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 6 mm × 6 mm) (board thickness: 1.6 mm)	_	_	150		
Thermal resistance (junction to lead)	R _{th (j-l)}	Junction to lead of cathode side	_	_	30	°C/W	

Marking

Abbreviation Code	Part No.			
5	CUS05			

Standard Soldering Pad



Handling Precaution

Schottky barrier diodes have reverse current characteristic compared to the other diodes.

There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage. This device is VF-IRRM trade-off type, lower VF higher IRRM; therefore, thermal runaway might occur when voltage is applied. Please take forward and reverse loss into consideration during design.

The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.

The following are the general derating methods that we recommend for designing a circuit using this device.

VRRM: Use this rating with reference to the above. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

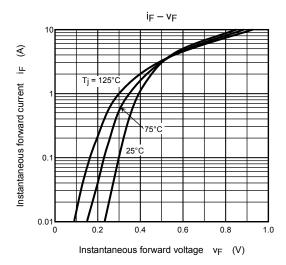
IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV) and T_j be below 100°C. When using this device, take the margin into consideration by using an allowable Tamax-IF(AV) curve.

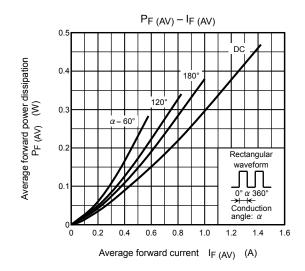
IFSM: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

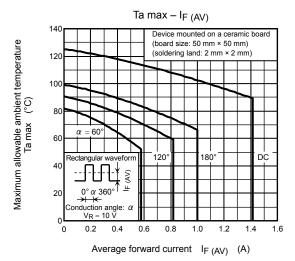
 T_j : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at T_i of below 100°C.

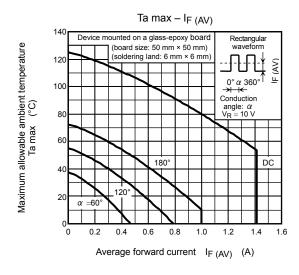
Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, please design a circuit board and a soldering land size to match the appropriate thermal resistance value

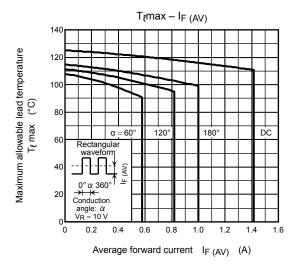
Refer to the Rectifiers databook for further information.

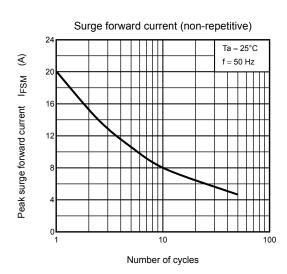




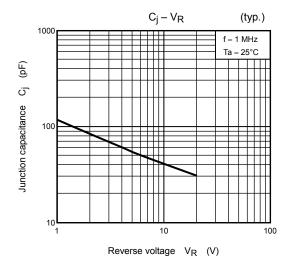


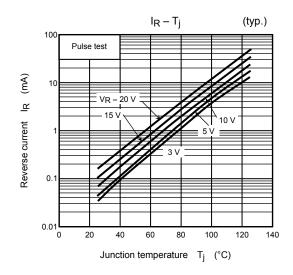


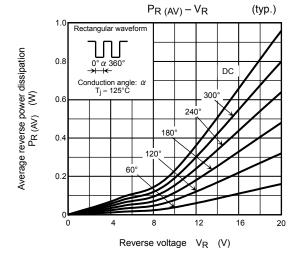


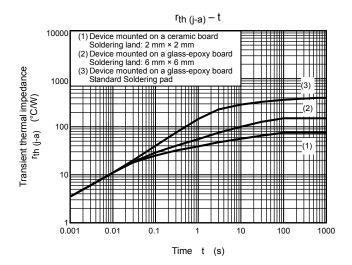


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4

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